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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A flat transponder having an electronic circuit which is arranged in ~~one of a layer or in and~~ a layer composite and which contains at least one chip and conductor tracks or conductor wires, characterized in that the circuit is arranged in or on a circuit carrier ~~[(7)]~~ made of plastic, on whose two larger opposite outer surfaces a paper layer ~~[(6)]~~ is applied by lamination ~~is in each case applied.~~
2. (Currently Amended) The transponder as claimed in claim 1, ~~characterized in that wherein~~ the paper layer ~~(6) consists of~~ comprises coated paper.
3. (Currently Amended) The transponder as claimed in claim 1 ~~[[or 2]]~~, ~~characterized in that~~ wherein the circuit carrier ~~(7) consists of~~ comprises a layer in which an antenna ~~[(2)]~~ and a module ~~[(3)]~~ having module connections ~~[(4)]~~ are embedded.
4. (Currently Amended) The transponder as claimed in claim 1 ~~[[or 2]]~~, ~~characterized in that~~ wherein the circuit carrier ~~[(7)]~~ comprises at least two plastic films ~~[(7.1, 7.2)]~~, between which there are arranged an antenna ~~[(2)]~~ and a module ~~[(3)]~~ having module connections ~~[(4)]~~.
5. (Currently Amended) The transponder as claimed in ~~one of the preceding claims~~ claim 1, ~~characterized in that wherein~~ the circuit carrier ~~(7) consists of~~ comprises polyethylene.
6. (Currently Amended) The transponder as claimed in ~~one of the preceding claims~~ claim 1, ~~characterized in that wherein~~ notches ~~[(11)]~~ are introduced into at least one paper layer ~~[(6)]~~.

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7. (Currently Amended) The transponder as claimed in claim 6, ~~characterized in that~~ wherein the notches ~~[[(11)]]~~ are made in the form of trenches having one of parallel ~~[[or]]~~ and V-shaped limits.
8. (Currently Amended) The transponder as claimed in claim 6 ~~[[or 7]]~~, ~~characterized in that~~ wherein the depth of the notches ~~[[(11)]]~~ is less than the thickness of the paper layer ~~[[(6)]]~~.
9. (Currently Amended) The transponder as claimed in claim 6 ~~[[or 7]]~~, ~~characterized in that~~ wherein the notches ~~[[(11)]]~~ penetrate through the paper layer ~~[[(6)]]~~ and penetrate into the adjacent layer of the circuit carrier ~~[[(7)]]~~.
10. (Currently Amended) The transponder as claimed in ~~one of claims 6 to 9~~ claim 6, ~~characterized in that~~ wherein the notches ~~[[(11)]]~~ are applied at least one of at different intervals ~~and/or~~ and with a different depth on the various sections of the paper layer ~~[[(6)]]~~ in order to create surface regions ~~[[of]]~~ having at least one of different flexibility ~~and/or~~ and different flexibility directions.
11. (Currently Amended) The transponder as claimed in ~~one of the preceding claims~~ claim 6, ~~characterized in that~~ wherein the notches ~~[[(11)]]~~ are arranged in the form of visible cut patterns ~~or~~ symbols.
12. (Currently Amended) The transponder as claimed in ~~one of claims 1 to 11~~ claim 1, ~~characterized in that~~ wherein the circuit is enclosed completely by the material of the circuit carrier ~~[[(7)]]~~.
13. (Currently Amended) The transponder as claimed in ~~one of claims 1 to 11~~ claim 1, ~~characterized in that~~ wherein the module (3) ~~consists of~~ comprises a rigid body which is arranged

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in an aperture which is located in the circuit carrier [(7)] and the paper layer [(6)] located above the ~~latter~~paper layer.

14. (Currently Amended) A method for the production of a transponder ~~as claimed in one of claims 1 to 13~~having an electronic circuit which is arranged in one of a layer and a layer composite and which contains at least one chip and conductor tracks or conductor wires, the method comprising:

~~characterized in that the fitting the circuit is fitted~~ in or on a circuit carrier [(7)] made of plastic; and

~~in each case applying a paper layer (6) is applied~~ to both sides of the circuit carrier [(7)] by lamination.

15. (Currently Amended) The method as claimed in claim 14, ~~characterized in that~~ wherein the lamination ~~is carried out by means of~~ comprises:

hot pressing [[of]] the circuit carrier [(7)] and paper layers [(6)] together between one of laminating plates [[or]] and laminating rolls.

16. (Currently Amended) The method as claimed in claim 14, ~~characterized in that~~ wherein notches [(11)] are introduced on at least one surface side of the laminate [(1)].

17. (Currently Amended) The method as claimed in claim 16, ~~characterized in that~~ wherein the notches [(11)] are produced during the lamination by ~~means of~~ notching webs fitted in an elevated manner to one of [[the]] laminating plates [[or]] and laminating rolls, the form of said notching webs corresponds to the form of the notches [(11)] to be produced.

18. (Currently Amended) The method as claimed in claim 16, ~~characterized in that~~ wherein the notches [(11)] are introduced by ~~means of~~ at least one of knife [[or]] and saw cuts after the lamination.

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19. (Currently Amended) The method as claimed in claim 16, ~~characterized in that~~ wherein the notches ~~[[(11)]]~~ are introduced by ~~means of~~ laser cuts after the lamination.

20. (Currently Amended) The method as claimed in claim 16, ~~characterized in that~~ wherein the notches~~[[(11)]]~~ are produced by ~~combined introduction by means of~~ at least one of a knife, saw, and laser introduced by laminating plates during the lamination ~~and by knife, saw or laser cuts after the~~ lamination.